

METHOD AND STRUCTURE FOR THE ADHESION BETWEEN DIELECTRIC LAYERS

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Abstract

A method for forming an adhesion between dielectric layers, it includes forming a first dielectric layer and forming a second dielectric
10 layer having a first portion and a second portion. The first portion is on the first dielectric layer and the second portion is on the first portion. The first portion and second portion are formed by an in-situ method. The first portion has at least one of the following a dielectric constant, hardness or SiCH₃/SiO area ratio, which is higher than the second
15 portion. A structure of enhanced-inter-adhesion dielectric layers includes a first dielectric layer and a second dielectric layer having a first portion on the first dielectric layer, and a second portion on the first portion. Herein, the first portion has a dielectric constant around 2.8 to 3.5 higher than second portion.

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